RELIABILITY REPORT

FOR

MAX3878EHJ

PLASTIC ENCAPSULATED DEVICES

June 22, 2003

MAXIM INTEGRATED PRODUCTS

120 SAN GABRIEL DR.

SUNNYVALE, CA 94086

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Conclusion

The MAX3878 successfully meets the quality and reliability standards required of all Maxim products. In addition, Maxim's continuous reliability monitoring program ensures that all outgoing product will continue to meet Maxim's quality and reliability standards.

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I. Device Description

A. General

The MAX3878 is a compact, low-power clock recovery and data retiming ICs for 2.488Gbps SONET/ SDH applications. The fully integrated phase-locked loop (PLL) recovers a synchronous clock signal from the serial NRZ data input, which is retimed by the recovered clock. An additional 2.488Gbps serial input is available for system loopback diagnostic testing, or this input can be connected to a 155MHz reference clock to maintain a valid clock output in the absence of data transitions. The MAX3878 provides vertical threshold and phase-adjust control to optimize system BER in DWDM applications.

This device provides both loss-of-lock (LOL-bar) and loss-of-signal (LOS) monitors. Differential PECL outputs are provided for both clock and data signals on the MAX3878.

The MAX3878 is designed for both section-regenerator and terminal-receiver applications in OC-48/STM-16 transmission systems. The jitter performance exceeds all of the SONET/SDH specifications. This device operates from a single +3.0V to +3.6V supply over a -40°C to +85°C temperature range. Typical power consumption is only 540mW with a +3.3V supply. It is available in a 32-pin TQFP-EP package with an exposed pad, as well as in die form.

B. Absolute Maximum Ratings

Item	Rating
Supply Voltage, VCC	-0.5V to +5.5V
Input Voltage Levels (SDI+, SDI-, SLBI+, SLBI-)	(VCC - 0.8V) to (VCC + 0.5V)
Input Current Levels (SDI+, SDI-, SLBI+, SLBI-)	-16mA to +10mA
PECL Output Current Levels(SDO+, SDO-, SCLKO+, SCLKO-)	0mA to 56mA
CML Output Current Level (SDO+, SDO-, SCLKO+, SCLKO-)	±22mA
Current into LOS, LOL	-600µA to +4mA
Voltage at LOS, SIS, PHADJ, THADJ, CPWD+, CPWD-, LOL, FIL+, FIL-, LREF	-0.5V to (VCC + 0.5V)
Operating Temperature Range	-40°C to +85°C
Operating Junction Temperature Range (die)	-55°C to +150°C
Storage Temperature Range	-65°C to +150°C
Processing Temperature (die)	+400°C
Lead Temperature (soldering, 10s)	+300°C
Continuous Power Dissipation (TA = +70°C)	
32-Pin TQFP-EP	1444mW
Derates above +70°C	
32-Pin TQFP-EP	22.8mW/°C

II. Manufacturing Information

A. Description/Function:	2.5Gbps, +3.3V Clock and Data Retiming ICs with Vertical Threshold Adjust
B. Process:	GST-2 (High Speed Double Poly-Silicon Bipolar Process)
C. Number of Device Transistors:	1561
D. Fabrication Location:	Oregon, USA
E. Assembly Location:	Philippines
F. Date of Initial Production:	June, 2001

III. Packaging Information

A. Package Type:	**32 Lead TQFP-EP (Thin Quad Flat Pack, Exposed Pad)**
B. Lead Frame:	Copper
C. Lead Finish:	Solder Plate
D. Die Attach:	Silver-filled Epoxy
E. Bondwire:	Gold (1.2 mil dia.)
F. Mold Material:	Epoxy with silica filler
G. Assembly Diagram:	Buildsheet # 05-7001-0450
H. Flammability Rating:	Class UL94-V0
I. Classification of Moisture Sensitivity per JEDEC standard JESD22-A112:	Level 1

IV. Die Information

A. Dimensions:	91 x 90 mils
B. Passivation:	Si_3N_4 (Silicon nitride)
C. Interconnect:	Poly / Au
D. Backside Metallization:	None
E. Minimum Metal Width:	1.4 microns (as drawn)
F. Minimum Metal Spacing:	1.4 microns (as drawn)
G. Bondpad Dimensions:	5 mil. Sq.
H. Isolation Dielectric:	SiO_2
I. Die Separation Method:	Wafer Saw

V. Quality Assurance Information

A. Quality Assurance Contacts:

Jim Pedicord	(Manager, Rel Operations)
Bryan Preeshl	(Executive Director of QA)
Kenneth Huening	(Vice President)

B. Outgoing Inspection Level: 0.1% for all electrical parameters guaranteed by the Datasheet.
0.1% For all Visual Defects.

C. Observed Outgoing Defect Rate: < 50 ppm

D. Sampling Plan: Mil-Std-105D

VI. Reliability Evaluation

A. Accelerated Life Test

The results of the 150°C biased (static) life test are shown in **Table 1**. Using these results, the Failure Rate (λ) is calculated as follows:

$$\lambda = \frac{1}{MTTF} = \frac{1.83}{192 \times 9823 \times 87 \times 2}$$

(Chi square value for MTTF upper limit)

Thermal acceleration factor assuming a 0.8eV activation energy

$\lambda = 5.58 \times 10^{-9}$ $\lambda = 5.58$ F.I.T. (60% confidence level @ 25°C)

This low failure rate represents data collected from Maxim's reliability qualification and monitor programs. Maxim also performs weekly Burn-In on samples from production to assure the reliability of its processes. The reliability required for lots which receive a burn-in qualification is 59 F.I.T. at a 60% confidence level, which equates to 3 failures in an 80 piece sample. Maxim performs failure analysis on lots exceeding this level. Maxim also performs 1000 hour life test monitors quarterly for each process. This data is published in the Product Reliability Report (**RR-B3A**).

B. Moisture Resistance Tests

Maxim evaluates pressure pot stress from every assembly process during qualification of each new design. Pressure Pot testing must pass a 20% LTPD for acceptance. Additionally, industry standard 85°C/85%RH or HAST tests are performed quarterly per device/package family.

C. E.S.D. and Latch-Up Testing

The HF67 die type has been found to have all pins able to withstand a transient pulse of +/-1500V, per Mil-Std-883 Method 3015 (reference attached ESD Test Circuit). Latch-Up testing has shown that this device withstands a current of ±250mA.

Table 1
Reliability Evaluation Test Results

MAX3878EHJ

TEST ITEM	TEST CONDITION	FAILURE IDENTIFICATION	SAMPLE SIZE	NUMBER OF FAILURES
Static Life Test (Note 1)				
	Ta = 150°C Biased Time = 192 hrs.	DC Parameters & functionality	87	0
Moisture Testing				
Pressure Pot	Ta = 121°C P = 15 psi. RH= 100% Time = 168hrs.	DC Parameters & functionality	77	0
85/85	Ta = 85°C RH = 85% Biased Time = 1000hrs.	DC Parameters & functionality	77	0
Mechanical Stress				
Temperature Cycle	-65°C/150°C 1000 Cycles Method 1010	DC Parameters & functionality	77	0

Note 1: Life Test Data may represent plastic D.I.P. qualification lots.
Note 2: Generic Package/Process data.

Attachment #1

TABLE II. Pin combination to be tested. 1/ 2/

	Terminal A (Each pin individually connected to terminal A with the other floating)	Terminal B (The common combination of all like-named pins connected to terminal B)
1.	All pins except V_{PS1} 3/	All V_{PS1} pins
2.	All input and output pins	All other input-output pins

1/ Table II is restated in narrative form in 3.4 below.
2/ No connects are not to be tested.
3/ Repeat pin combination I for each named Power supply and for ground

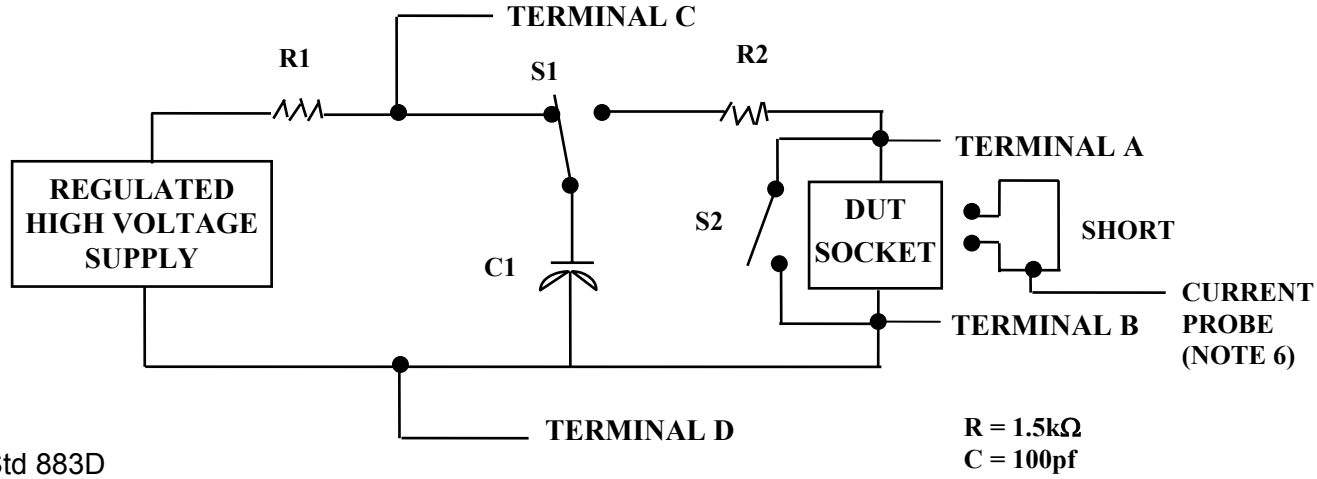
(e.g., where V_{PS1} is V_{DD}, V_{CC}, V_{SS}, V_{BB}, GND, $+V_S$, $-V_S$, V_{REF}, etc).

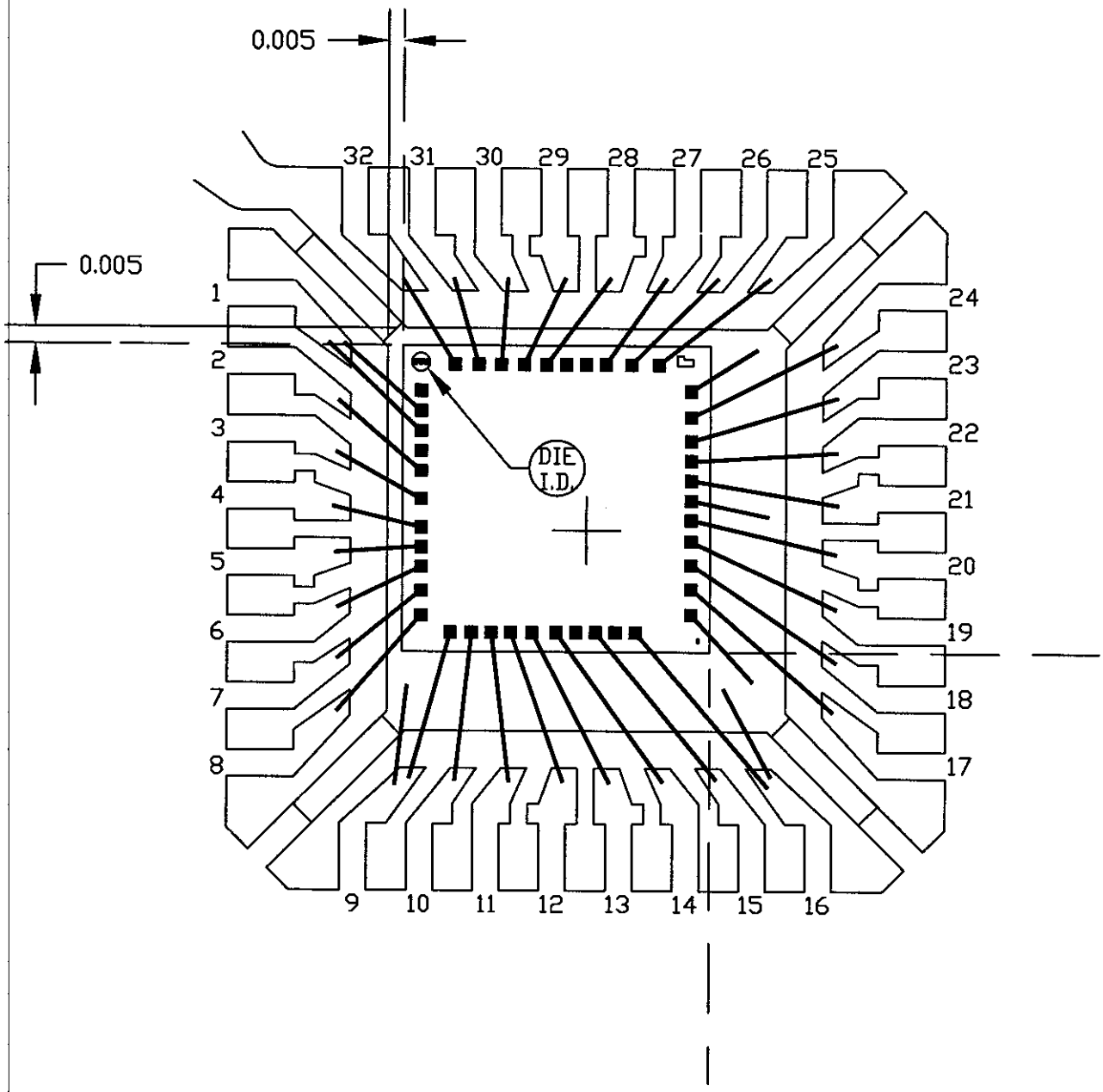
3.4 Pin combinations to be tested.

a. Each pin individually connected to terminal A with respect to the device ground pin(s) connected to terminal B. All pins except the one being tested and the ground pin(s) shall be open.

b. Each pin individually connected to terminal A with respect to each different set of a combination of all named power supply pins (e.g., V_{SS1}, or V_{SS2} or V_{SS3} or V_{CC1}, or V_{CC2}) connected to terminal B. All pins except the one being tested and the power supply pin or set of pins shall be open.

c. Each input and each output individually connected to terminal A with respect to a combination of all the other input and output pins connected to terminal B. All pins except the input or output pin being tested and the combination of all the other input and output pins shall be open.





PKG. CODE: H32E-5		SIGNATURES	DATE	MAXIM CONFIDENTIAL & PROPRIETARY	
CAV./PAD SIZE: 118×118	PKG. DESIGN			BOND DIAGRAM #: 05-7001-0450	REV: A